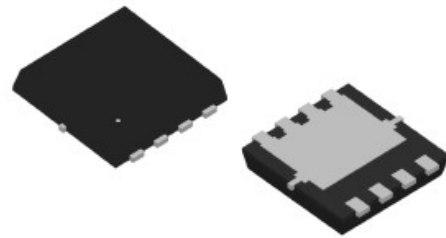


## WNM3038

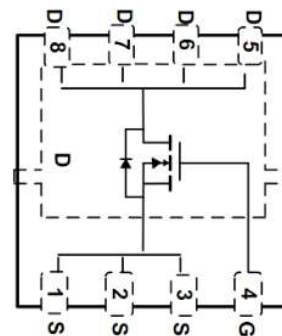
### SingleN-Channel, 30V, 22A, Power MOSFET

<https://www.omnivision-group.com>

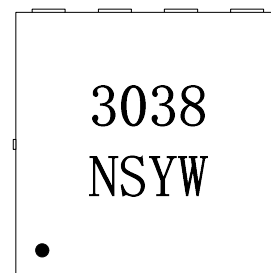
V <sub>DS</sub> (V)	Typical R <sub>DS(on)</sub> (mΩ)
30	6.0 @ V <sub>GS</sub> =10V
	8.5 @ V <sub>GS</sub> =4.5V



PDFN3333-8L



Pin configuration (Top view)



3038 =Device Code  
NS =Special Code  
Y = Year  
W = Week(A~z)

#### Marking

### Description

The WNM3038 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM3038 is Pb-free.

### Features

- Trench Technology
- Super high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package PDFN3333-8L

### Applications

- DC/DC converters
- Power supply converters circuit
- Load/Power Switching for portable device

### Order information

Device	Package	Shipping
WNM3038-8/TR	PDFN3333-8L	2500/Tape&Reel

**Absolute Maximum ratings**

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current <sup>d</sup>	$I_D$	$T_C=25^\circ\text{C}$	22
		$T_C=70^\circ\text{C}$	22
Pulsed Drain Current <sup>c</sup>	$I_{DM}$	80	A
Continuous Drain Current	$I_{DSM}$	$T_A=25^\circ\text{C}$	16
		$T_A=70^\circ\text{C}$	13
Avalanche Energy $L=0.3\text{mH}$	$E_{AS}$	38	mJ
Power Dissipation <sup>b</sup>	$P_D$	$T_C=25^\circ\text{C}$	15.4
		$T_C=70^\circ\text{C}$	9.9
Power Dissipation <sup>a</sup>	$P_{DSM}$	$T_A=25^\circ\text{C}$	3.7
		$T_A=70^\circ\text{C}$	2.4
Operating Junction Temperature	$T_J$	-55 to 150	$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to 150	$^\circ\text{C}$

**Thermal resistance ratings**

Single Operation					
Parameter	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$R_{\theta JA}$	$t \leq 10\text{ s}$	27	34	$^\circ\text{C/W}$
		Steady State	54	67	
Junction-to-Case Thermal Resistance	$R_{\theta JC}$	6.5	8.1		

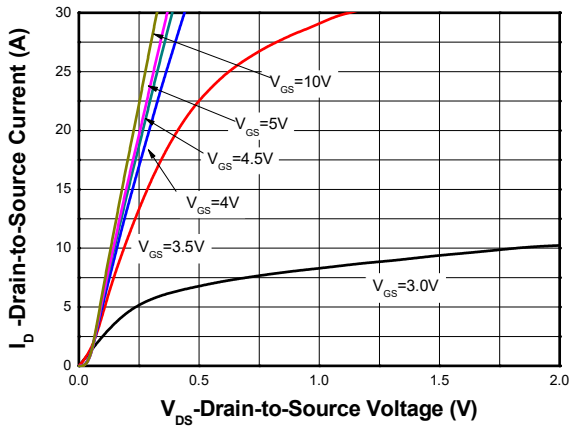
**Note:**

- a The value of  $R_{\theta JA}$  is measured with the device mounted on 1-inch<sup>2</sup> (6.45cm<sup>2</sup>) with 2oz.(0.071mm thick) Copper pad on a 1.5\*1.5 inch<sup>2</sup>, 0.06-inch thick FR4 PCB, in a still air environment with  $T_A = 25^\circ\text{C}$ . The power dissipation  $P_{DSM}$  is based on  $R_{\theta JA} t \leq 10\text{s}$  value and the  $T_{J(MAX)}=150^\circ\text{C}$ . The value in any given application is determined by the user's specific board design.
- b The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^\circ\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- c Repetitive rating, ~10us pulse width, duty cycle ~1%, keep initial  $T_J = 25^\circ\text{C}$ , the maximum allowed junction temperature of  $150^\circ\text{C}$ .
- d The maximum current rating by source bonding technology.
- e The static characteristics are obtained using ~380us pulses, duty cycle ~1%.

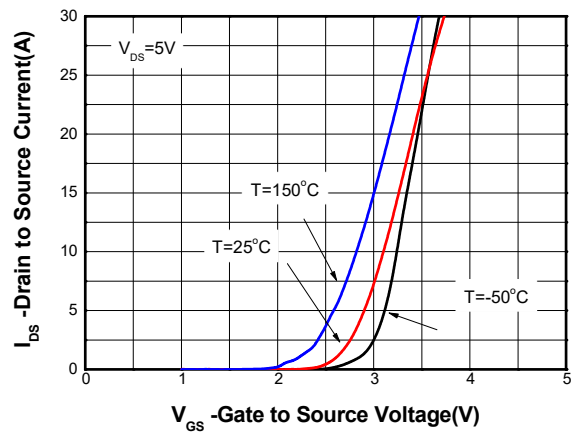
Electronics Characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$			1	$\mu\text{A}$
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$			$\pm 100$	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	1.2	1.8	2.5	V
Drain-to-source On-resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 10\text{ A}$		6.0	8.0	m $\Omega$
		$V_{GS} = 4.5\text{ V}, I_D = 8\text{ A}$		8.5	12.5	
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}, V_{DS} = 15\text{ V}$		1300		pF
Output Capacitance	$C_{OSS}$			193		
Reverse Transfer Capacitance	$C_{RSS}$			152		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V}, I_D = 10\text{ A}$		28		nC
Threshold Gate Charge	$Q_{G(TH)}$			2.3		
Gate-to-Source Charge	$Q_{GS}$			6.5		
Gate-to-Drain Charge	$Q_{GD}$			5		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_d(ON)$	$V_{GS} = 10\text{ V}, V_{DS} = 15\text{ V}, R_L = 1\ \Omega, R_G = 3\ \Omega$		4.0		ns
Rise Time	$t_r$			17.2		
Turn-Off Delay Time	$t_d(OFF)$			16.4		
Fall Time	$t_f$			8		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = 1\text{ A}$		0.7	1.2	V

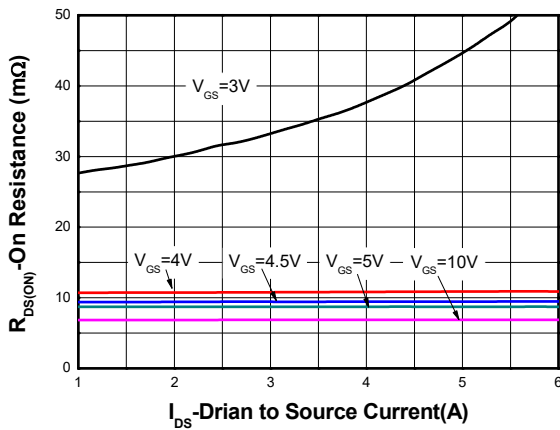
Typical Characteristics (Ta=25°C, unless otherwise noted)



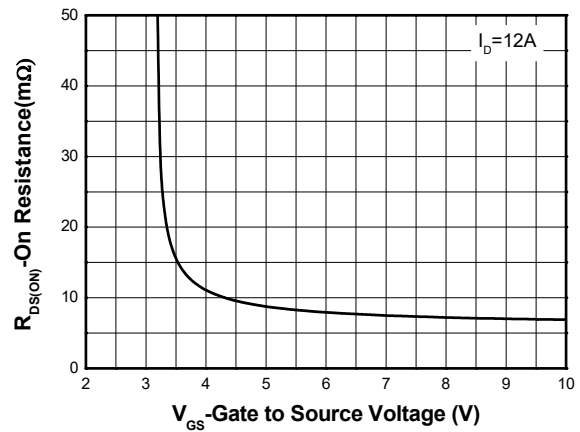
Output Characteristics <sup>e</sup>



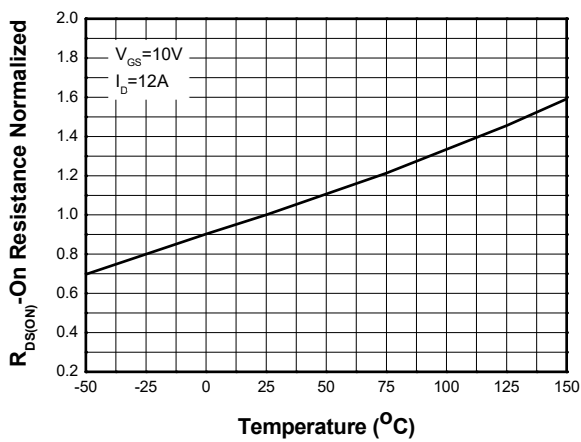
Transfer Characteristics <sup>e</sup>



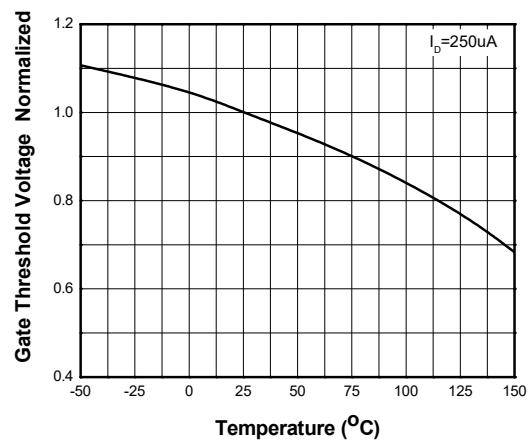
On-Resistance vs. Drain Current <sup>e</sup>



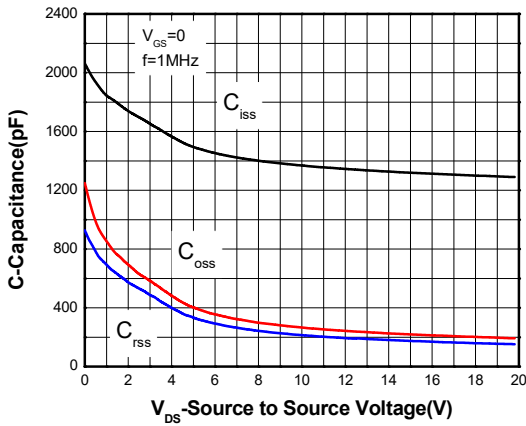
On-Resistance vs. Gate-to-Source Voltage <sup>e</sup>



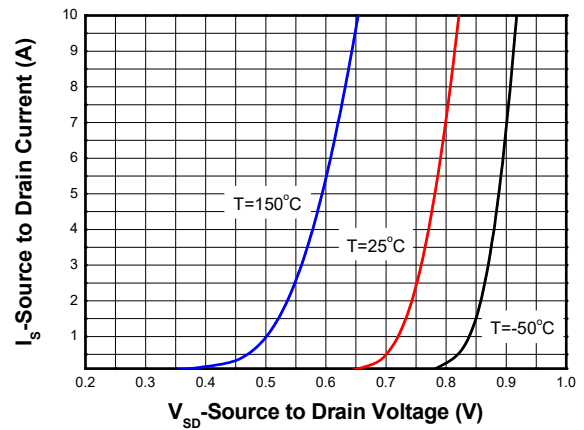
On-Resistance vs. Junction Temperature <sup>e</sup>



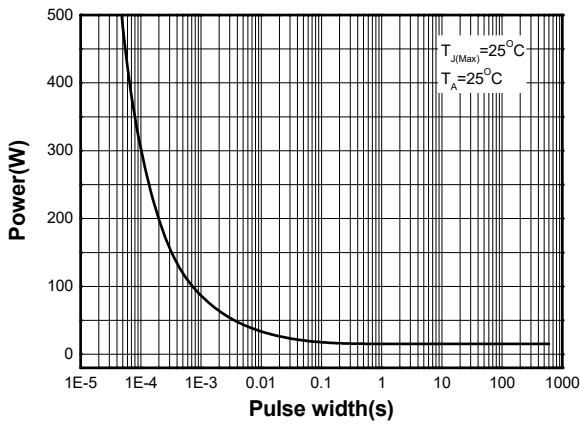
Threshold voltage vs. Temperature



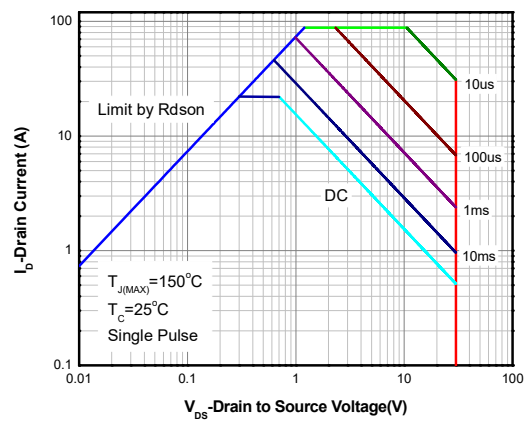
Capacitance



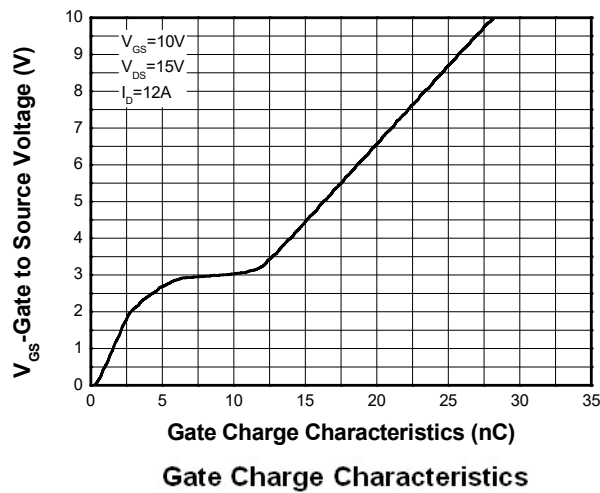
Body Diode Forward Voltage<sup>e</sup>



Single pulse power

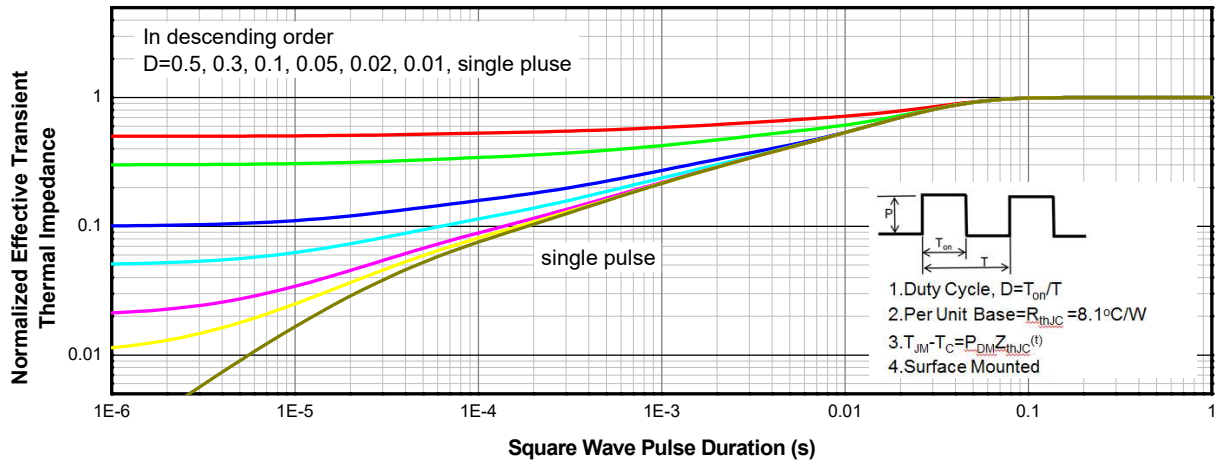


Safe operating power

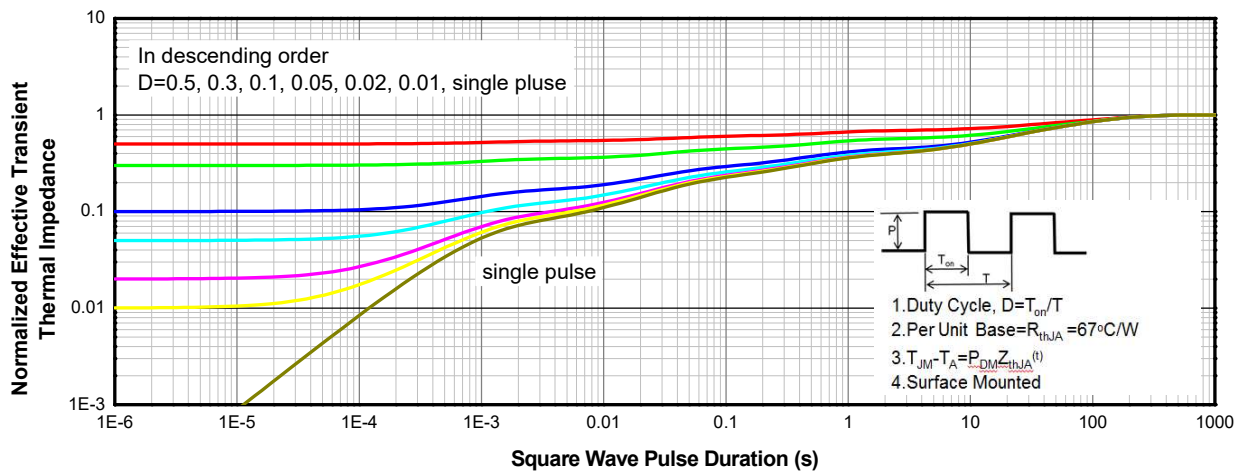


Gate Charge Characteristics

### Transient Thermal Response (Junction-to-Case)

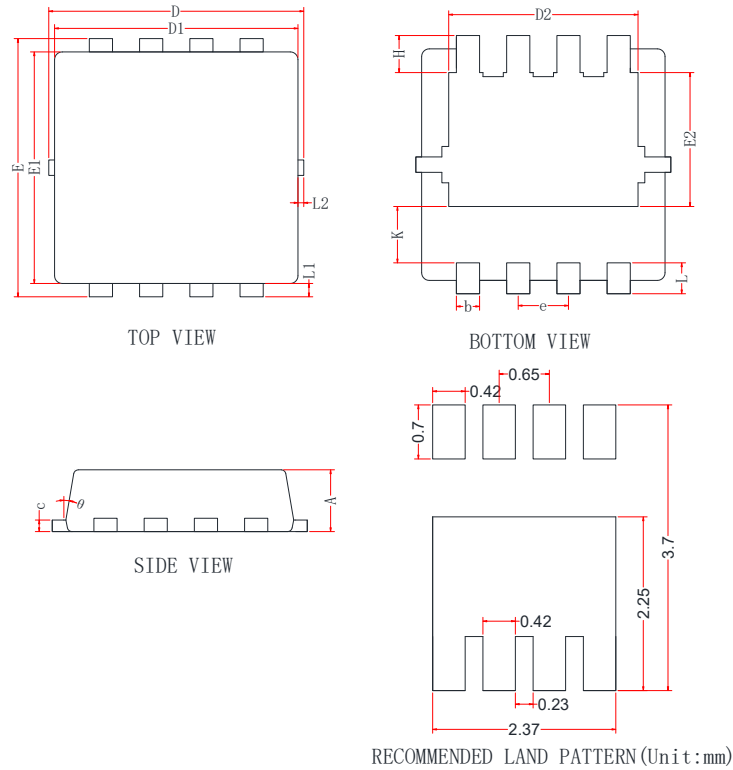


### Transient Thermal Response (Junction-to-Ambient)



PACKAGE OUTLINE DIMENSIONS

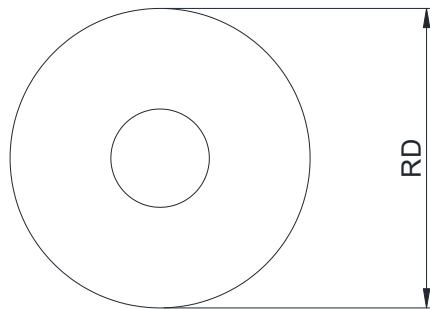
PDFN3333-8L



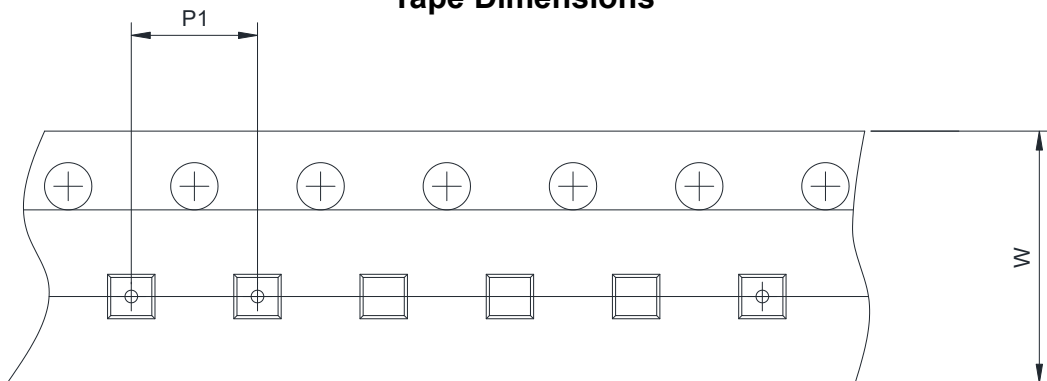
Symbol	Dimensions in Millimeters		
	Min.	Typ.	Max.
A	0.70	0.80	0.90
b	0.25	0.30	0.35
c	0.14	0.15	0.20
D	3.10	3.30	3.50
D1	3.05	3.15	3.25
D2	2.35	2.45	2.55
e	0.55	0.65	0.75
E	3.10	3.30	3.50
E1	2.90	3.00	3.10
E2	1.64	1.74	1.84
H	0.32	0.42	0.52
K	0.59	0.69	0.79
L	0.25	0.40	0.55
L1	0.10	0.15	0.20
L2	-	-	0.15
$\theta$	8°	10°	12°

**TAPE AND REEL INFORMATION**

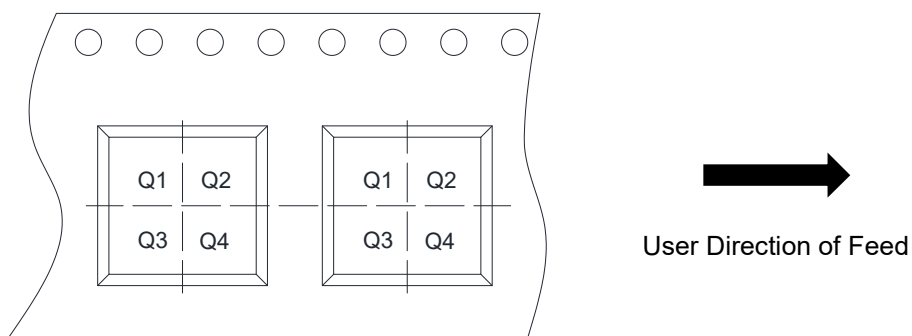
**Reel Dimensions**



**Tape Dimensions**



**Quadrant Assignments For PIN1 Orientation In Tape**



RD	Reel Dimension	<input type="checkbox"/> 7inch	<input checked="" type="checkbox"/> 13inch
W	Overall width of the carrier tape	<input type="checkbox"/> 8mm	<input checked="" type="checkbox"/> 12mm <input type="checkbox"/> 16mm
P1	Pitch between successive cavity centers	<input type="checkbox"/> 2mm	<input type="checkbox"/> 4mm <input checked="" type="checkbox"/> 8mm
Pin1	Pin1 Quadrant	<input checked="" type="checkbox"/> Q1	<input type="checkbox"/> Q2 <input type="checkbox"/> Q3 <input type="checkbox"/> Q4



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